

Form 1449 (Modified)
Information Disclosure Statement By Applicant
(Use Several Sheets if Necessary)

Atty Docket No.
NSC1P223/P05081
Applicant:
BRANCHEVSKY
Filing Date
12/06/01

Application No.:
10/006,482

Group
3729

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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
TPN	1	4,082,906	04/04/78	Amin et al.	428	539	02/14/77
TPN	2	4,471,406	09/11/84	Sawairi	361	328	09/29/82
TPN	3	4,517,406	05/14/85	Erdle	174	72	05/14/84
TPN	4	4,734,818	03/29/88	Hernandez et al.	361	306	03/19/87
TPN	5	4,740,863	04/26/88	Langlois	361	309	05/15/87
TPN	6	4,748,537	05/31/88	Hernandez et al.	361	306	05/08/87
TPN	7	5,027,253	06/25/91	Lauffer et al.	361	321	02/09/90
TPN	8	5,036,424	07/30/91	Yokotani et al.	361	321	05/18/90
TPN	9	5,046,236	09/10/91	Wada et al.	29	610.1	10/10/90
TPN	10	5,319,517	06/07/94	Nomura et al.	361	321.4	03/29/93

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation
							Yes No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
TPN	17	Delaney, <i>Characterization and Performance Prediction for Integral Capacitors in Low Temperature Co-Fired Ceramic Technology</i> , IEEE Transactions on Advanced Packaging, Vol. 22, No. 1, February 1999, pg. 68-77
TPN	18	Delaney, <i>Characterisation of the Electrical Performance of Buried Capacitors and Resistors in Low Temperature Co-Fired (LTCC) Ceramic</i> , IEEE Electronic Components and Technology Conference, 1998, pg. 900-908
TPN	19	Scrantom, <i>Manufacture of Embedded Integrated Passive Components into Low Temperature Co-Fired Ceramic Systems</i> , International Symposium on Microelectronics, 1998, pg. 459-466
Examiner		Date Considered
	<i>Tanya Nguyen</i>	<i>10/31/03</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant

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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
TTN	11	5,661,882	09/02/97	Alexander	29	25.42	06/30/95
	12	5,687,055	11/11/97	Miki	361	305	01/04/95
	13	5,736,448	04/07/98	Saia et al.	438	393	12/04/95
	14	6,011,683	01/04/00	Dat	361	306.1	01/30/98
	15	6,061,228	05/09/00	Palmer et al.	361	306.2	04/28/98
TTN	16	6,252,761	06/26/01	Branchevsky	361	321.2	09/15/99

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
TTN	20	Müller, <i>3D-Integration of Passive RF-Components in LTCC</i> , Technical University of Ilmenau, Germany, pg. 211-216
TTN	21	Wersing, <i>Integrated Passive Components Using Low Temperature Cofired Ceramics</i> , International Symposium on Microelectronics, 1998, pg. 193-199
TTN	22	Drüe, <i>RF Models of Passive LTCC Components in the Lower Gigahertz-Range</i> , Applied Microwave & Wireless, Technical University of Ilmenau, Germany, April 1998, pg. 26-35
TTN	23	U.S. Patent Application No. 09/632,361, entitled "Embedded Green Multi-Layer Ceramic Chip Capacitor in a Low-Temperature Co-Fired Ceramic (LTCC) Substrate, filed August 3, 2000
Examiner	<i>Taylor Nguyen</i>	
	Date Considered	
	<i>10/31/01</i>	

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